sPHENIX INTT

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Assembly status in Taiwan

Half-ladder assembly

	Total	Good	not yet bonded	bad
chip to HDI	14	5	3	6
sensor to HDI	7	3	3	1
thermal cycle	3	3	0	0
encapsulation	8	8	0	0

No new case

dummy sensor

Sensor to chip wire bond result :
<6 un-bonded : 13 half-ladders
>20 un-bonded : 3 half-ladders

- Components inventory
  - HDI : 30 (batch 1-B : 21)
  - Chip : 2256 (~86 modules)
  - Stave : 25 (batch 1)
  - Sensor : 64 sets

Back up